

### Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC



SOD-123FL

印字: A7

### Mechanical Data

- **Case:** SOD-123FL molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per JESD22-B102
- **Polarity:** Laser band denotes cathode end
- **Weight:** 0.017gram

### Major Ratings and Characteristics

$I_{F(AV)}$	1A
$V_{RRM}$	50 V to 1000 V
$I_{FSM}$	30 A
$I_R$	5 $\mu$ A
$V_F$	1.1 V
$T_j$ max.	150 °C

### Maximum Ratings & Thermal Characteristics

( $T_A = 25\text{ °C}$  unless otherwise noted)

Items	Symbol	A1	A2	A3	A4	A5	A6	A7	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	1							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	30							A
Thermal resistance from junction to ambient <sup>(1)</sup>	$R_{\theta JA}$	150							°C/ W
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							°C

Note 1: Mounted on P.C.B. with 0.036 x 0.06" (0.9 x 1.5mm) copper pad areas.

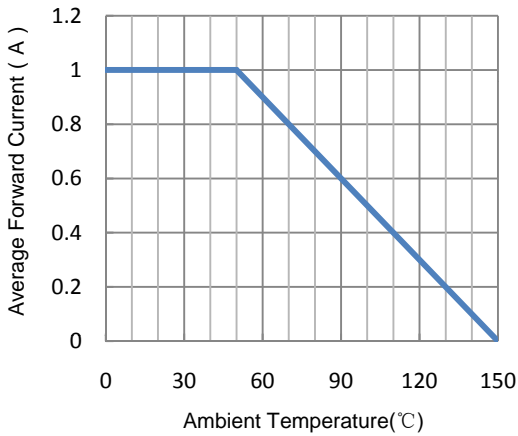
### Electrical Characteristics ( $T_A = 25\text{ °C}$ unless otherwise noted)

Items	Test conditions	Symbol	Min	Type	Max	UNIT
Instantaneous forward voltage	$I_F=1.0A^{(2)}$	$V_F$	-	0.98	1.10	V
Reverse current	$V_R=V_{DC}$	$I_R$	-	-	5	$\mu$ A
					50	

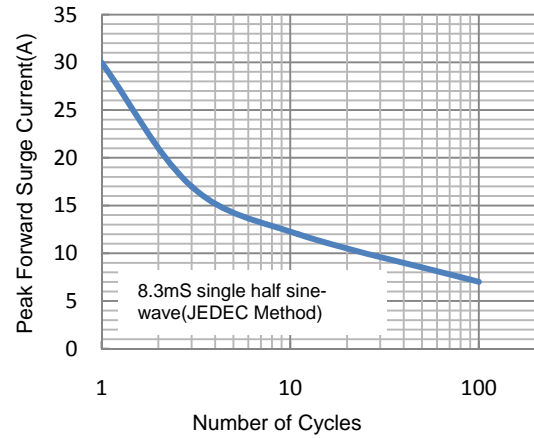
Note 2: Pulse test:300 $\mu$ s pulse width,1% duty cycle.

### Characteristic Curves ( $T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

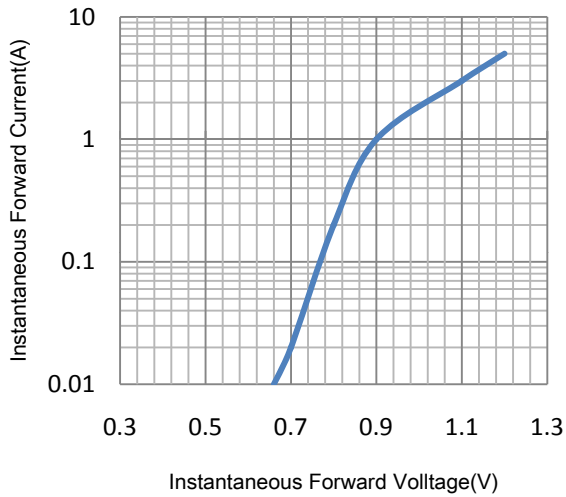
**Fig.1 Forward Current Derating Curve**



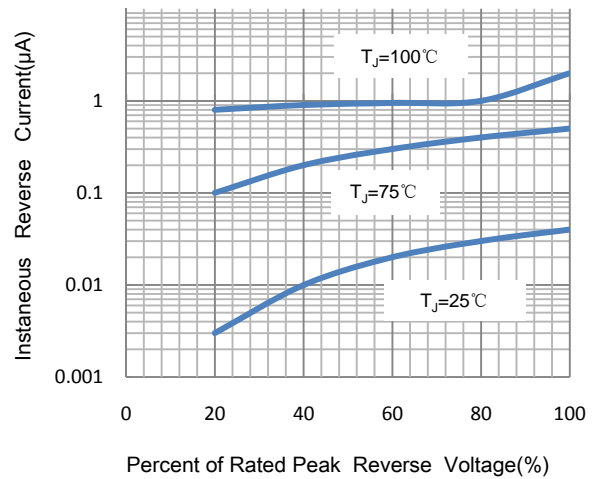
**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current**



**Fig.3 Typical Instantaneous Forward Characteristics**

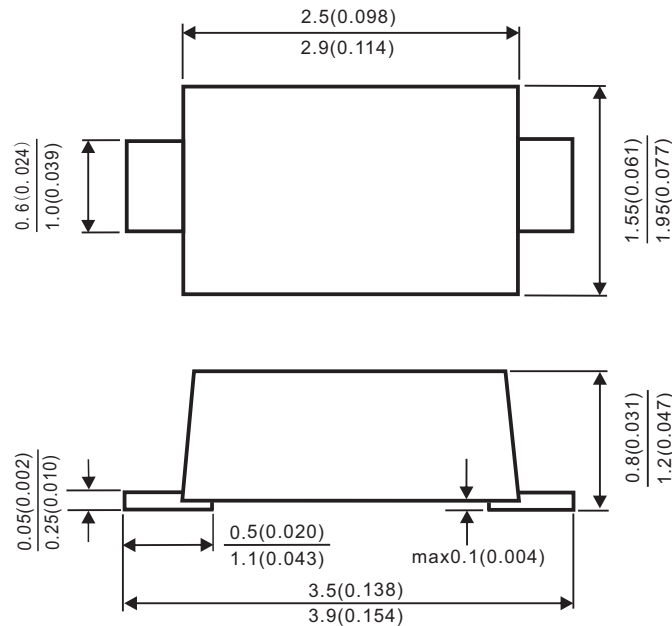


**Fig.4 Typical Reverse Characteristics**



### Package Outline

SOD-123FL



Dimensions in millimeters and(inches)

### Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.

$I_{F(AV)}$  : We recommend that the worst case current be no greater than 80% .

$T_J$  : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a  $T_J$  of below 125°C.

- TRR is registered trademark of Zhejiang TRR Microelectronics Inc. Zhejiang TRR Microelectronics Inc reserves the right to make changes to any product in this specification without notice.
- Zhejiang TRR Microelectronics Inc does not assure any liability arising out of the applications or use of any product described in this specification.
- Zhejiang TRR Microelectronics Inc advises customers to obtain the latest version of the device information before placing orders to verify that the required information is current.